

Features

- Low RDS(on) & FOM
- · Extremely Low Switching Loss
- · Excellent Stability and Uniformity
- · Fast Switching and Soft Recovery
- Halogen Free Available Upon Request By Adding Suffix "-HF"
- · Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- · Moisture Sensitivity Level 1

Maximum Ratings

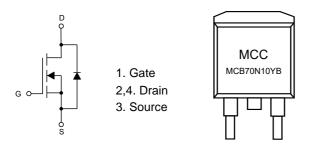
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- · Thermal Resistance: 1°C/W Junction to Case
- Thermal Resistance:15°C/W Junction to Ambient (t≤10s)⁽¹⁾
- Thermal Resistance: 60°C/W Junction to Ambient (Steady-State)⁽¹⁾

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Volltage		V _{GS}	±20	V
Continuous Drain	T _C =25°C	1	70	Α
Current ⁽²⁾	T _C =100°C	– I _D	44	Α
Pulsed Drain Current ⁽³⁾		I _{DM}	280	Α
Total Power Dissipation ⁽⁴⁾		P _D	125	W
Single Pulsed Avalanche Energy ⁽⁵⁾		E _{AS}	200	mJ

Note:

- 1. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 2. The maximum current rating is package limited.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_D is based on max. junction temperature, using junction-case thermal resistance.
- 5. V_{DD} =50V, R_G =25 Ω , L=0.5mH, starting T_J =25 °C.

Internal Structure and Marking Code

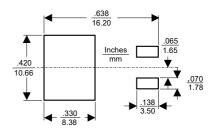


N-CHANNEL MOSFET

D2-PAK

	DIMENSIONS					
DIM INCHE		HES	MM		NOTE	
DIIVI	MIN	MAX	MIN	MAX	NOTE	
Α	0.331	0.370	8.40	9.40		
В	0.378	0.417	9.60	10.60		
С	0.165	0.189	4.20	4.80		
D	0.027	0.037	0.68	0.94		
E	0.045	0.055	1.14	1.40		
G	0.010		2.54		TYP.	
Н	0.096	0.134	2.43	3.40		
J	0.011	0.025	0.28	0.64		
K	0.071	0.131	1.80	3.32		
S	0.575	0.625	14.60	15.87		
V	0.042	0.058	1.07	1.47		
W	0.000	0.010	0.00	0.25		

Suggested Solder Pad Layout



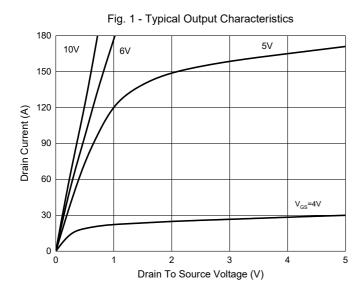


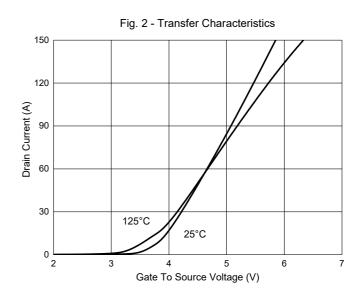
Electrical Characteristics @ 25°C (Unless Otherwise Specified)

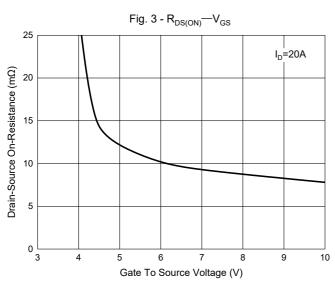
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics					1		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	100			V	
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			1	μA	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2	2.8	4	V	
Drain-Source On-Resistance		V _{GS} =10V, I _D =20A		7.2	8.6	mΩ	
	R _{DS(on)}	V _{GS} =6V, I _D =20A		10	13	mΩ	
Gate Resistance	R _g	f=1MHz, Open drain		0.68		Ω	
Diode Characteristics							
Continuous Body Diode Current	Is				70	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A			1.3	V	
Reverse Recovery Time	t _{rr}	1 -004 -11 /14-4004/		51.5		ns	
Reverse Recovery Charge	Q _{rr}	I _S =20A, dI _F /dt=100A/μs		84		nC	
Dynamic Characteristics							
Input Capacitance	C _{iss}			2270			
Output Capacitance	C _{oss}	V _{DS} =50V,V _{GS} =0V,f=1MHz		797		pF	
Reverse Transfer Capacitance	C _{rss}			36		1	
Total Gate Charge	Qg			32			
Gate-Source Charge	Q _{gs}	V _{DS} =50V,V _{GS} =10V,I _D =25A		11.1		nC	
Gate-Drain Charge	Q_{gd}			4.78			
Turn-On Delay Time	t _{d(on)}			51			
Turn-On Rise Time	t _r	V _{GS} =10V, V _{DD} =50V,I _D =25A		14.4		no	
Turn-Off Delay Time	t _{d(off)}	R _{GEN} =2.2Ω		69.2		ns	
Turn-Off Fall Time	t _f			20.6			

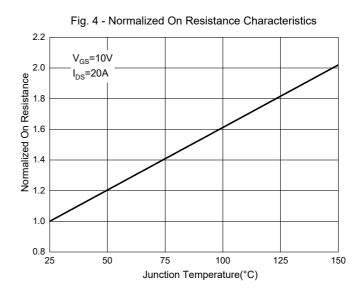


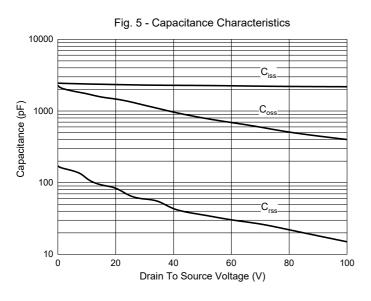
Curve Characteristics

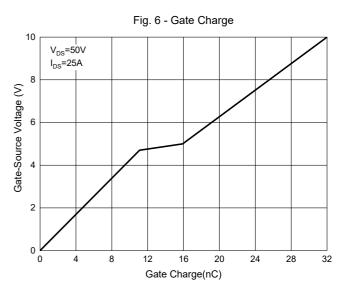














Curve Characteristics

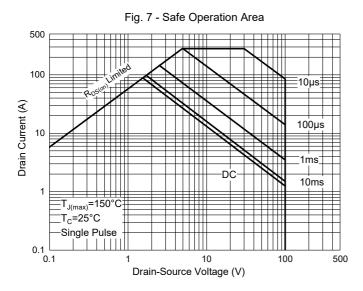
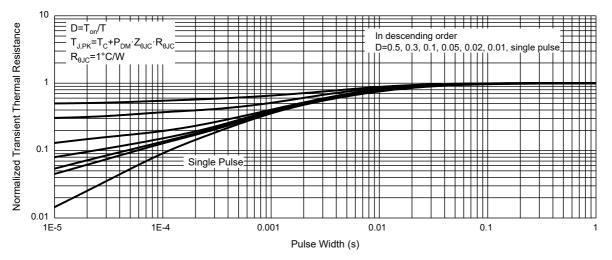


Fig. 8 - Normalized Transient Thermal Impedance



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Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 800pcs/Reel

Note: Adding "-HF" Suffix for Halogen Free, eg. Part Number-TP-HF

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